

## Product Brief

### 22nm Radiation Hardened Mixed-Signal ASIC Design Platform

DARE22G is a radiation-hardened ASIC design platform for space applications in GF 22nm FDSOI technology. It provides an extensive set of digital and analog IPs along with a design kit to support full-custom design of mixed-signal blocks. DARE22G standard cell libraries and IPs make use of several Radh-Hard-By-Design techniques to mitigate total ionizing dose and single-event effects in harsh environments.

#### Key Features

- TID tolerance up to 100 krad (SiO<sub>2</sub>)
- SEL hardening beyond 70 MeV·cm<sup>2</sup>/mg
- SEU hardened flip-flops
- SET hardened clock/asynchronous tree cells
- TMR support
- Multi-Vt and multi-Lg core cell variants enabling fine-grained power vs. delay trade-offs
- Multi-domain I/O support
- Multi-voltage programmable I/O interface
- Cold-spare LVCMOS IO, LVDS and SSTL
- Distributed power-on-control
- Wire-bonding and flip-chip enabled
- Inline and staggered pad arrangement
- Analog IP hardened against SET above 60 MeV·cm<sup>2</sup>/mg

#### Radiation Hardened IP

DARE22G offers an extensive range of libraries and IP blocks for the implementation of complex mixed-signal ASICs for radiation environment applications.

- High-density 10-track standard cell libraries
  - Multiple Vt (sLVT, LVT, RVT, HVT)
  - Multiple channel lengths (20/24/28 nm)
  - Conventional and Flipped Well
  - Up to 60 MeV·cm<sup>2</sup>/mg SEU/SET hardening
  - Special cells supporting TMR
- Multi-voltage I/O library
  - 1.8 V or 3.3 V signal interface
  - 2 – 24 mA programmable drive strength
  - Programmable input pull-up/pull-down
  - Fast speed and slew-rate controlled buffers
- DDR3-compliant SSTL\_15 library
  - 1600 Mbps data rate
- Wide-range programmable PLL
  - 8.929 – 2000 MHz output clock
  - 20 – 100 MHz reference clock
  - Single 0.8 V power supply
- LVDS transmitter/receiver
  - > 1 Gbps data rate
  - TIA/EIA-644-A-2001 compliant
  - Fail-safe input signal detection
- Bandgap-based 1.8 V IVREF
  - 0.6 V output reference voltage
  - 10 μA output reference current
  - Digitally trimmable

#### Deliverables

Logic synthesis is supported with front-end library views. Black-box views and ADK are provided to assist custom analog design.

- Analog Design Kit (Cadence IC6)
- Black-box CDL netlists
- OA symbol and abstract views
- Encrypted Spectre® netlists
- IBIS models (on demand)
- Synopsys Liberty files
- Compiled Synopsys libraries
- Verilog simulation models
- VITAL simulation models
- HTML datasheets
- User guides

#### Analog Design Kit

The DARE22G ADK extends the foundry PDK with additional features to assist full-custom designers in implementing radiation-hardened blocks compatible with DARE22G specifications:

- Schematic checks for Cadence IC6 Virtuoso®
- SET fault injection simulation toolkit for Cadence IC6 environment
- Radiation-hardened layout DRC rule deck for Siemens Calibre®

Technology	
Foundry	GF
Process	22FDX
Supported MiM	No (APMOM/MOM supported)
Supported metal stacks	10M_2Mx_6Cx_2Ix_LB 9M_2Mx_3Cx_2Bx_1Ix_1Ox_LB

Operating Conditions	
Core voltage	0.8 V
LVDS voltage	1.8 V
SSTL voltage	1.5 V (DDR3)
I/O voltage	1.8 V 3.3 V
Junction temperature	-40 – 125 °C
ESD protection	up to 2 kV (HBM)
TID tolerance	100 krad (SiO <sub>2</sub> )
SEL tolerance	> 70 MeV·cm <sup>2</sup> /mg
SEU tolerance	> 60 MeV·cm <sup>2</sup> /mg

## **Design Services**

Imec.IC-link offers design services to implement your radiation-hardened ASICs integrating existing DARE22G and customer-designed IPs. Special digital implementation methodologies are employed to deliver optimal TID and SEE performance.

Imec offers a broad range of chip services to support customers with manufacturing, assembling, testing and validating of flight models based on the DARE22G technology.

## **Support**

Further technical information or design service requests can be obtained at [dare@imec.be](mailto:dare@imec.be).

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